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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re U.S. Patent No. 6,756,665
Issued: June 29, 2004

Serial No: 10/635,564
Inventor: Nai-Shung CHANG
Title: INTEGRATED CIRCUIT PACKAGE STRUCTURE WITH HEAT
DISSIPATING DESIGN

REQUEST FOR REFUND OF PUBLICATION FEE

Mail Stop PGPUB

Director of the U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA. 22313-1450

Sir:

The publication fee of \$300, for the above-identified patent, was paid May 6, 2004, along with the issue fee.


The official filing receipt stated a projected publication date of July 15, 2004, but the application issued earlier on June 29, 2004 before publication of the application.

Therefore a refund of the publication fee of \$300 is requested and that it be deposited in our Deposit Account No. 02-0200.

Respectfully submitted,
BACON & THOMAS, PLLC

Date: November 29, 2004

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